



Evyap Sabun Malaysia Sdn Bhd

Evyap Oleo 1214

Lauric Myristic Acid

Product Data Sheet

CAS No. 90990-10-6

EINECS No. 292-771-7

Parameter	Unit	Specification
Appearance at 40 Deg. C	-	Clear liquid, free of foreign matter.
Colour, Lovibond, Max	In 5,1/4" Cell	Y=3.0; R=0.3
Acid Value	mg KOH/Gm	267 - 278
Sap. Value	mg KOH/Gm	268 - 279
Iodine Value, Max	Gms I ₂ / 100 Gms	0.2
Titre, Min	° C	32.0 – 36.0

Fatty Acid Composition	Unit	Specification
C 10	% by GC	2.0 Max
C 12	% by GC	70.0 Min
C 14	% by GC	20.0 - 28.0
C 16	% by GC	1.0 Max
Others	% by GC	1.0 Max

The above chart indicates typical available specifications. Customised specifications are also available.

APPLICATIONS

Preparation of cosmetics and personal care products, surfactant manufacture, candle, fabric softener, fatty alcohol, fatty amine, soap noodles for cosmetic and industrial application.

PACKING

Available in standard 180kg MS/HDPE drums, road tankers and bulk ISO container loads.

BEST BEFORE

24 months from the date of manufacturing in original containers, stored under standard conditions.

CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157.

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